

ABSTRACT

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A technique is closed for inspecting a spectrum of light reflected from a workpiece, such as a wafer, while the workpiece is being polished. The method includes: irradiating a plurality of film-thickness measurement points on the workpiece with light from an optical sensor head in each time segment during polishing of the workpiece; generating a plurality
10 of measurement spectra of reflected light from the plurality of film-thickness measurement points; calculating a plurality of features of the plurality of measurement spectra; performing data mapping by plotting, on a coordinate system, a plurality of measurement data points specified by a plurality of times at which the plurality of measurement spectra were generated and the plurality of features; determining a correction index value representing
15 the number of measurement data points existing within a threshold range defined on the coordinate system for each time segment; and determining whether the correction index value is within a correction management range.

FIG. 8